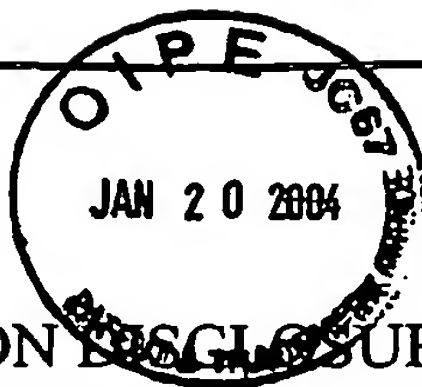


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## INFORMATION DISCLOSURE STATEMENT

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## U.S. PATENT DOCUMENTS

*EXAMINER INITIALS	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## FOREIGN PATENT DOCUMENTS

*Examiner Initials	Document Number	Publication Date	Country	Class	Subclass	Translation Yes No

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EXAMINER

*Chris Kalwood*

DATE CONSIDERED

*Sep 16, 2004*

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